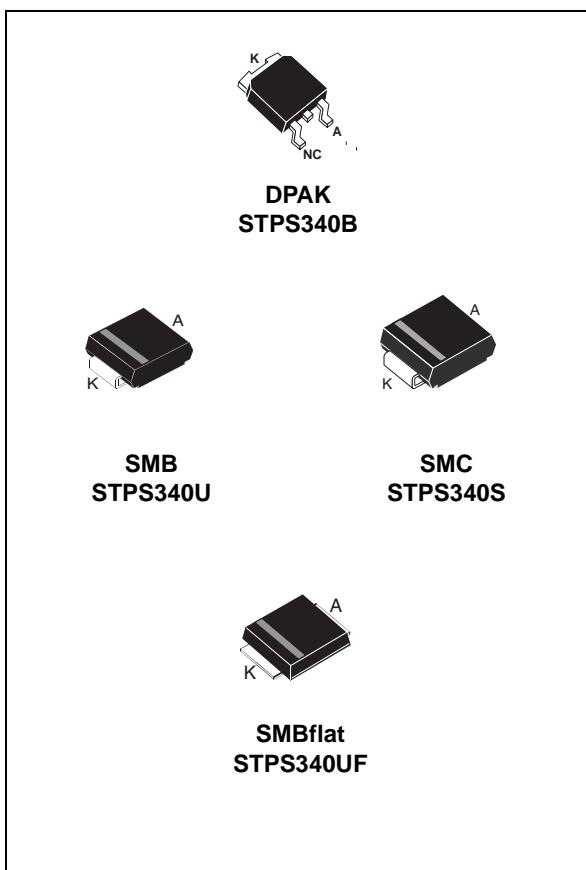


## SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER



### Features

- Very small conduction losses
- Negligible switching losses
- Low forward voltage drop
- Low thermal resistance
- Extremely fast switching
- Surface mounted device
- Avalanche capability specified
- ECOPACK®2 compliant component, STPS340UF

Table 1. Device summary

$I_{F(AV)}$	3 A
$V_{RRM}$	40 V
$T_j$ (max)	150 °C
$V_F$ (max)	0.57 V

# 1 Characteristics

**Table 2. Absolute Ratings (limiting values)**

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		40	V
$I_{F(RMS)}$	Forward rms current		DPAK	A
$I_{F(AV)}$	Average forward current	$T_c = 135^\circ\text{C} \delta = 0.5$	DPAK	
		$T_L = 105^\circ\text{C} \delta = 0.5$	SMB/SMC	A
		$T_L = 115^\circ\text{C} \delta = 0.5$	SMBflat	
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 \text{ ms sinusoidal}$	75	A
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 1 \mu\text{s} T_j = 25^\circ\text{C}$	1300	W
$T_{stg}$	Storage temperature range		-65 to + 150	°C
$T_j$	Operating junction temperature (1)		150	°C

1.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistance**

Symbol	Parameter		Value	Unit
$R_{th(j-l)}$	Junction to lead	SMB	25	°C/W
		SMBflat	15	
		SMC	20	
$R_{th(j-c)}$	Junction to case		DPAK	5.5
				°C/W

**Table 4. Static electrical characteristics**

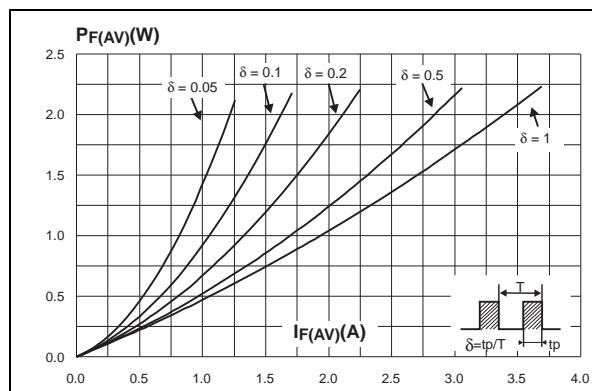
Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			20	µA
		$T_j = 125^\circ\text{C}$			2	10	mA
$V_F^{(1)}$	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 3 \text{ A}$			0.63	V
		$T_j = 125^\circ\text{C}$			0.52	0.57	
		$T_j = 25^\circ\text{C}$	$I_F = 6 \text{ A}$			0.84	
		$T_j = 125^\circ\text{C}$			0.63	0.72	

1. Pulse test:  $t_p = 380 \mu\text{s}, \delta < 2\%$

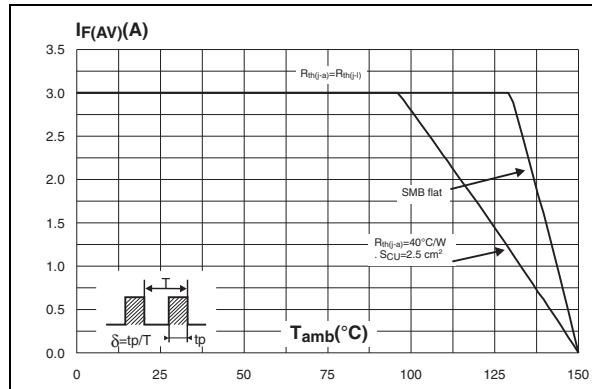
To evaluate the conduction losses use the following equation:

$$P = 0.42 \times I_{F(AV)} + 0.050 I_{F(RMS)}^2$$

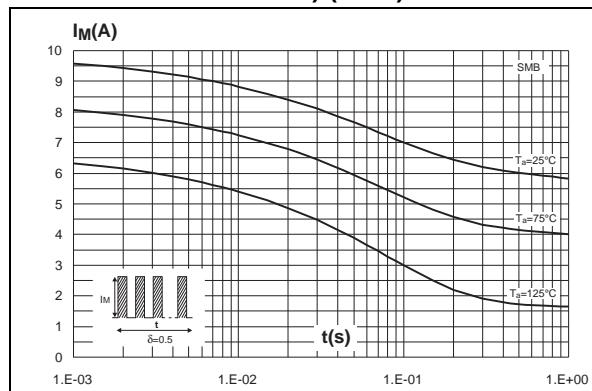
**Figure 1. Average forward power dissipation versus average forward current (per diode)**



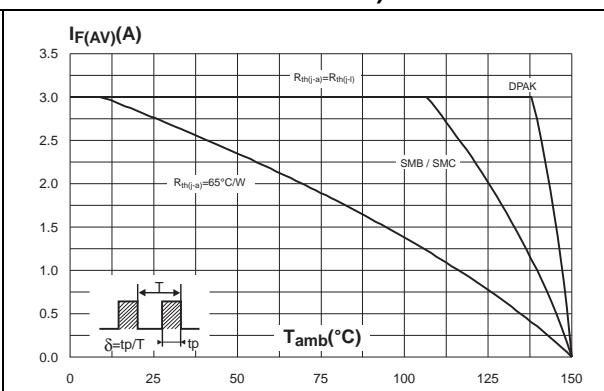
**Figure 3. Average forward current versus ambient temperature ( $\delta = 0.5$ , per diode) (SMBflat)**



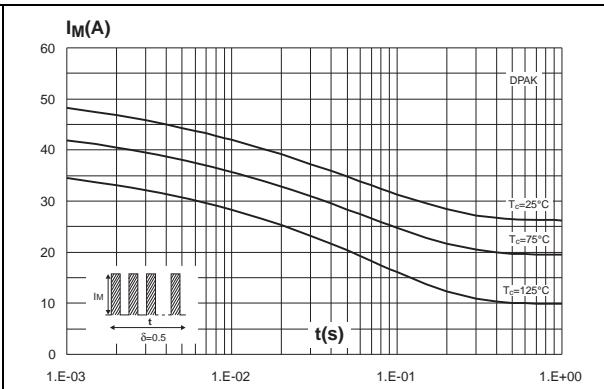
**Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values) (SMB)**



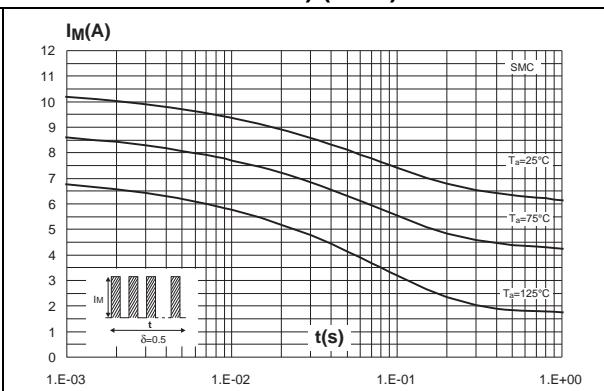
**Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ , per diode) (DPAK / SMB / SMC)**



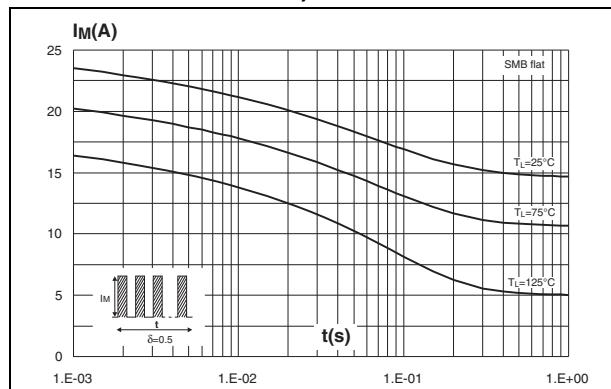
**Figure 4. Non repetitive surge peak forward current versus overload duration (maximum values) (DPAK)**



**Figure 6. Non repetitive surge peak forward current versus overload duration (maximum values) (SMC)**

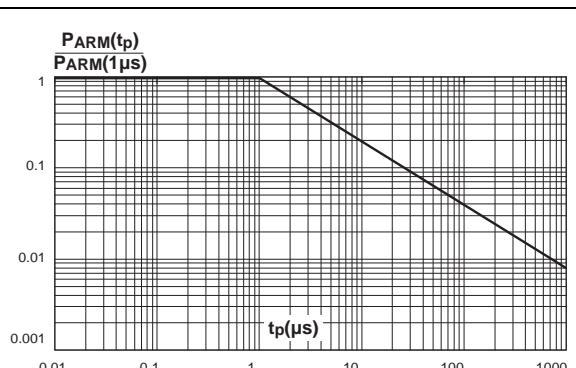


**Figure 7. Non repetitive surge peak forward current versus overload duration (maximum values) SMBflat**

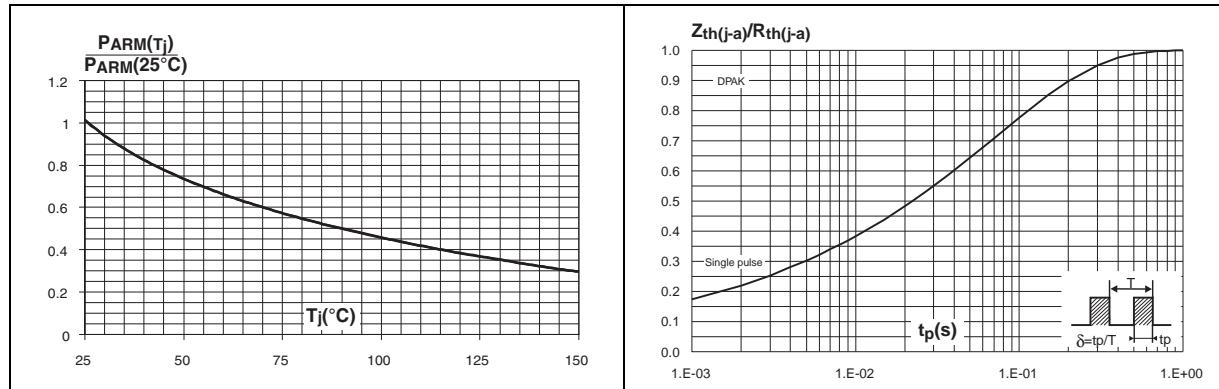


**Figure 9. Normalized avalanche power derating versus junction temperature**

**Figure 8. Normalized avalanche power derating versus pulse duration**

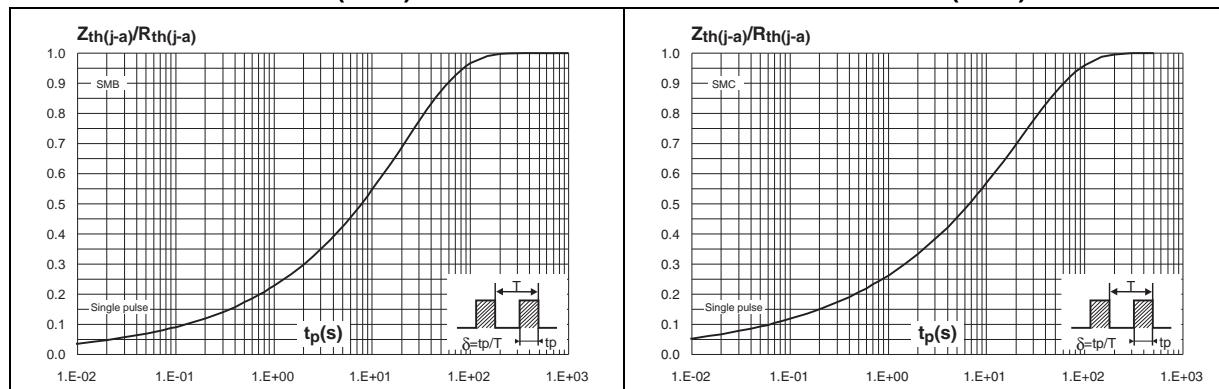


**Figure 10. Relative variation of thermal impedance junction to ambient versus pulse duration (DPAK)**

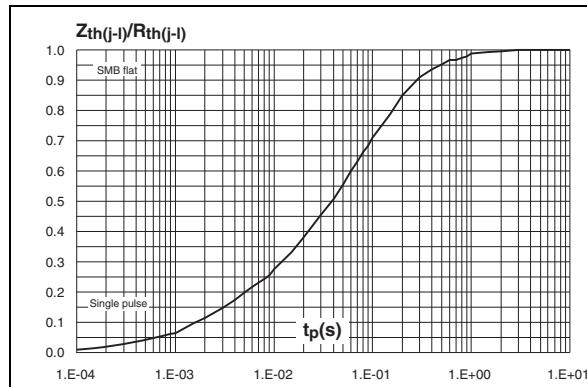


**Figure 11. Relative variation of thermal impedance junction to ambient versus pulse duration (SMB)**

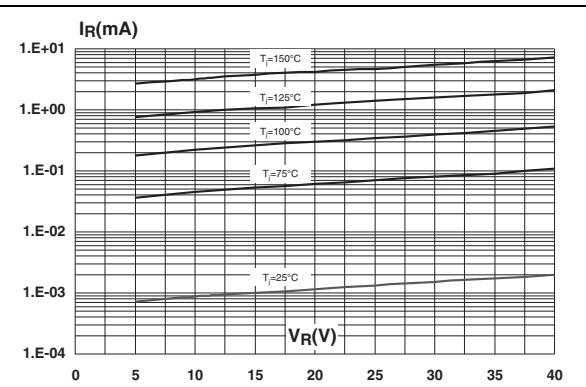
**Figure 12. Relative variation of thermal impedance junction to ambient versus pulse duration (SMC)**



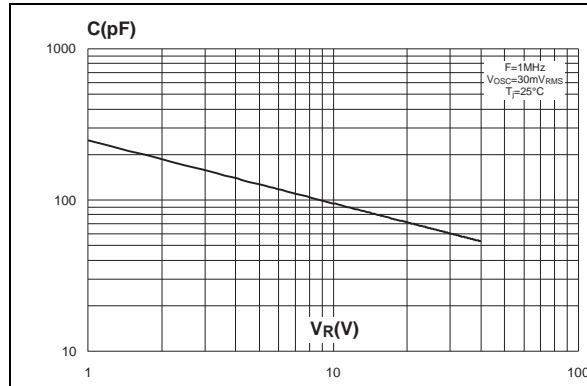
**Figure 13. Relative variation of thermal impedance junction to lead versus pulse duration - SMBflat**



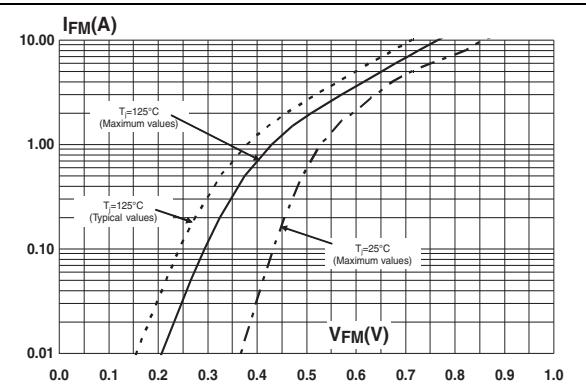
**Figure 14. Reverse leakage current versus reverse voltage applied (typical values)**



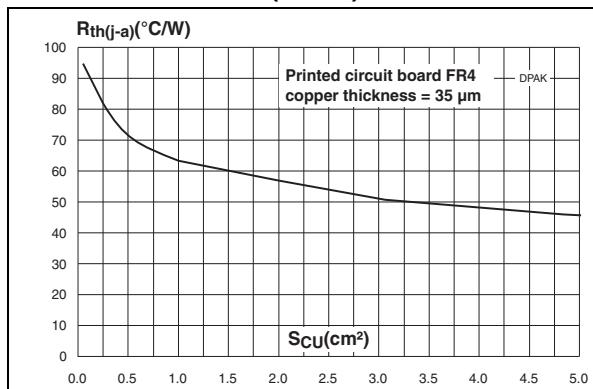
**Figure 15. Junction capacitance versus reverse voltage applied (typical values)**



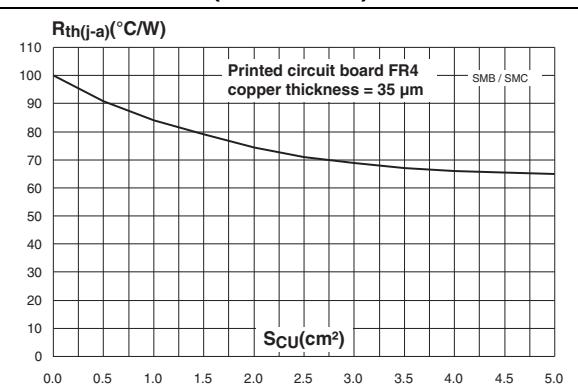
**Figure 16. Forward voltage drop versus forward current**



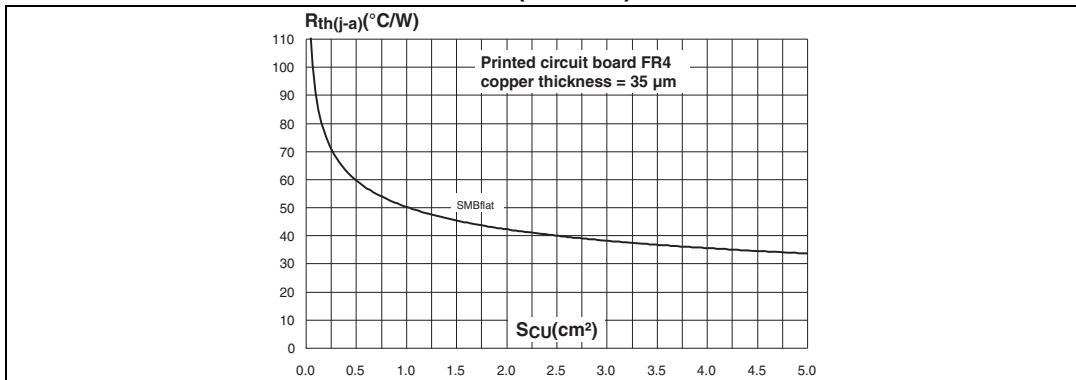
**Figure 17. Thermal resistance junction to ambient versus copper surface under each lead (DPAK)**



**Figure 18. Thermal resistance junction to ambient versus copper surface under each lead (SMB / SMC)**



**Figure 19. Thermal resistance junction to ambient versus copper surface under each lead (SMBflat)**

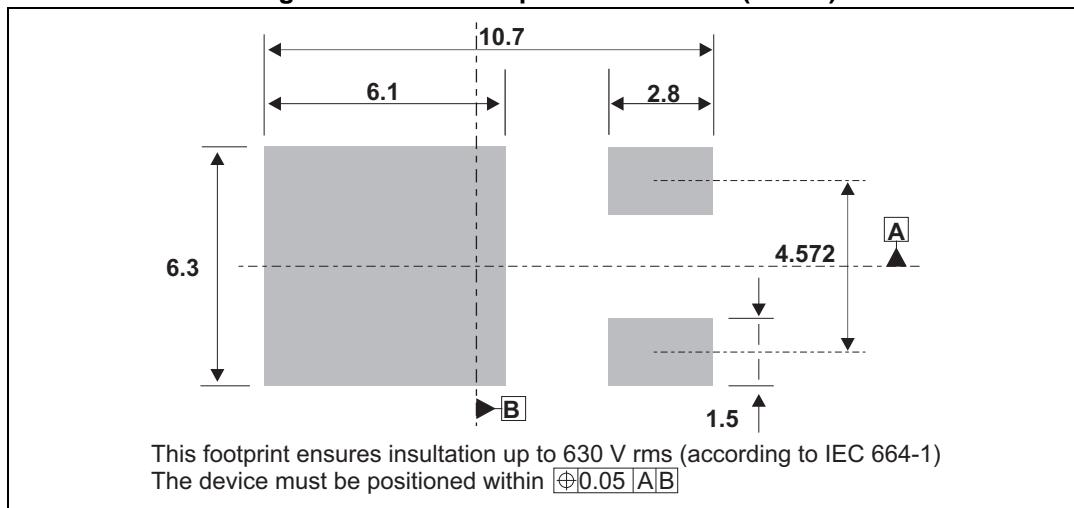


## 2 Package Information

**Table 5. DPAK dimension values**

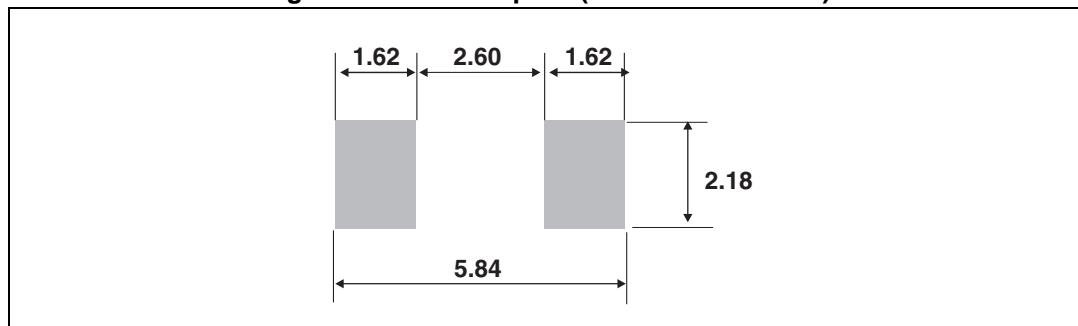
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.18		2.40	0.085		0.094
A1	0.90		1.1	0.035		0.043
A2	0.03		0.23	0.001		0.01
b	0.64		0.90	0.025		0.035
b4	4.95		5.46	0.195		0.215
c	0.46		0.61	0.018		0.024
c2	0.46		0.60	0.018		0.024
D	5.97		6.22	0.235		0.245
E	6.35		6.73	0.250		0.265
e1	4.4		4.7	0.173		0.185
H	9.35		10.34	0.368		0.407
L	1.0		1.78	0.039		0.070
L2			1.27			0.05
L4	0.6		1.02	0.024		0.040
V2	0°		8°	0°		8°

**Figure 20. DPAK footprint dimensions (in mm)**



**Table 6. SMB dimensions**

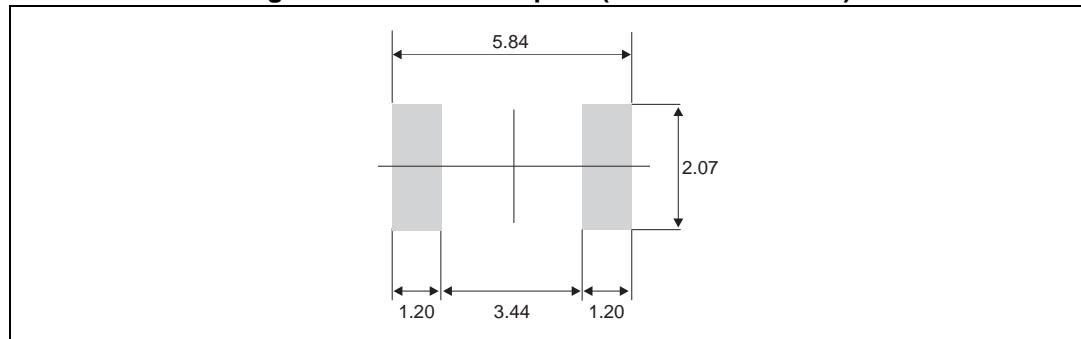
Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.40	0.006	0.016
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
D	3.30	3.95	0.130	0.156
L	0.75	1.50	0.030	0.059

**Figure 21. SMB footprint (dimensions in mm)**


**Table 7. SMBflat dimensions**

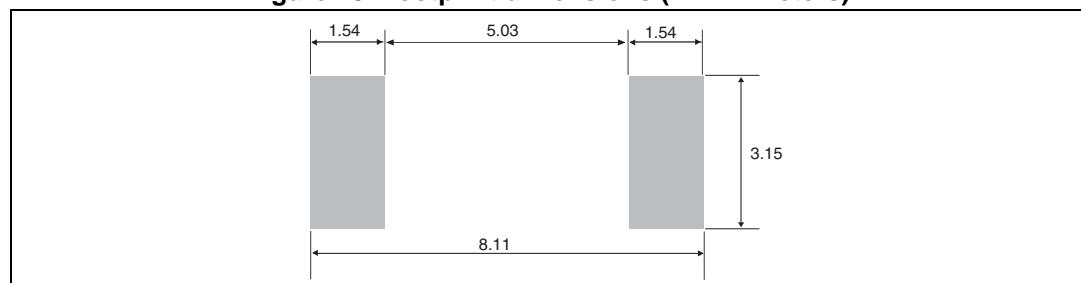
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90		1.10	0.035		0.043
b <sup>(1)</sup>	1.95		2.20	0.077		0.087
c <sup>(1)</sup>	0.15		0.40	0.006		0.016
D	3.30		3.95	0.130		0.156
E	5.10		5.60	0.200		0.220
E1	4.05		4.60	0.189		0.181
L	0.75		1.50	0.029		0.059
L1		0.40			0.016	
L2		0.60			0.024	

1. Applies to plated leads

**Figure 22. SMBflat footprint (dimensions in mm)**


**Table 8. SMC package dimensions**

Ref	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	2.90	3.2	0.114	0.126
c	0.15	0.41	0.006	0.016
E	7.75	8.15	0.305	0.321
E1	6.60	7.15	0.260	0.281
E2	4.40	4.70	0.173	0.185
D	5.55	6.25	0.218	0.246
L	0.75	1.40	0.030	0.063

**Figure 23. Footprint dimensions (in millimeters)**


### 3 Ordering information

**Table 9. Ordering information**

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS340	SS34	SMB	0.107 g	3000	Tape and reel
STPS340S	S34	SMC	0.243 g	3000	
STPS340B	S340	DPAK	0.30 g	75	Tube
STPS340B-TR				2500	Tape and reel
STPS340UF	FU34	ECOPACK®2 SMBflat	0.50 g	3000	Tape and reel

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[B0530WSQ-7-F](#) [PDS1040Q-13](#) [B160BQ-13-F](#) [SDM05U20CSP-7](#) [B140S1F-7](#)